

## CLAIMS

1. An inspecting device equipped with:
    - a performance substrate provided with a terminal for inspection;
    - a contactor substrate provided with a probe contacting an object to be inspected; and
    - a probe card,wherein said probe card is a multi-layered substrate in which a resin thin film is laminated on a ceramic board.
  2. An inspecting device equipped with:
    - a performance substrate provided with a terminal for inspection;
    - a contactor substrate provided with a probe contacting an object to be inspected; and
    - a probe card intervening between said probe of said contactor substrate and said terminal of said performance substrate,wherein said probe card is a multi-layered substrate in which a resin thin film is laminated on a ceramic board.
  3. An inspecting device equipped with:
    - a performance substrate provided with a terminal for inspection;
    - a contactor substrate provided with said probe contacting an object to be inspected; and
    - a probe card electrically connected to said probe of said contactor substrate,said inspecting device being constituted such that the object to be inspected is placed between said performance substrate and said probe card,
- wherein said probe card is a multi-layered substrate in which a resin thin film is laminated on a ceramic board.

4. The inspecting device according to any of claims 1 to 3,  
wherein the ceramic board of said probe card comprises  
non-oxide ceramic.
- 5 5. The inspecting device according to any of claims 1 to 4,  
wherein said resin thin film comprises thermosetting  
resin.
6. A probe card for the use of inspecting integrated circuits  
10 formed on a semiconductor-wafer,  
a resin insulating layer and a conductor circuit are  
serially formed in alternate fashion and in repetition on a  
ceramic board.
- 15 7. The probe card according to claim 6,  
wherein a conductor-filled through hole is formed in said  
ceramic board.
8. The probe card according to claim 6 or 7,  
20 wherein the resultant conductor circuits formed through  
said resin layer are interconnected each other by a via hole.
9. The probe card according to any of claims 6 to 8,  
wherein said ceramic board comprises non-oxide ceramic.
- 25 10. The probe card according to any of claims 6 to 9,  
wherein said resin layer comprises thermosetting resin.
11. The probe card according to any of claims 6 to 10,  
30 wherein said ceramic board is in a disc shape.
12. The probe card according to any of claims 6 to 11,  
wherein said resin layer is formed so as to cover the whole  
of at least one of main faces of said ceramic board.